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U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office

To the Honorable Commissioner of Pate	ached original documents or copy thereof.		
Name of conveying party(ies)	2. Name and address of receiving party(ies)		
Akihito NAKAYAMA, Kenji SHINTANI, Shunsuke KOHAMA, Yuk HASHIMOTO, Hideo KATO	Name: Sony Precision Engineering Center (S) Pte. Ltd. 52 Tuas Avenue 9 Singapore 639193		
Additional name(s) of conveying party(ies) attached? Yes <u>X</u> No	Disk Ware Co. Ltd. Nakoji Kiba Bldg. 2F		
3. Nature of conveyance:	1-4-12 Kiba, Koto-ku, *okyo 135-0042 Japan		
X Assignment Security Agreement	and		
Merger Change of Name Other	Sony Corporation 7-35 Kitashinagawa 6-chome Shinagawa-ku, Yo∢yo 141 Japan		
Execution Date(s): <u>November 2, November 2, November 16, November 16, and November 17, 1998</u>	Additional name(s) & address(es) at ached? Yes _x No		
4. Application number(s) or patent number(s):			
If this document is being filed together with a new application, the execution date of the application is:			
A. Patent Application No.(s) <u>09/182,179</u> filed <u>October 29, 1998</u>			
Additional numbers attached? Yes X No			
<ol> <li>Name and address of party to whom correspondence concerning document should be mailed:</li> </ol>	6. Total number of applications and patents involved		
Name: WILLIAM S. FROMMER Internal Address: FROMMER LAWRENCE & HAUG LLP	7. Total fee (37 CFR 3.41)		
Street Address: 745 FIFTH AVENUE	deposit account 50-0320		
City: <u>NEW YORK</u> State: <u>N.Y.</u> Zip: <u>10151</u>	<ol> <li>Deposit account number:         (Attach duplicate copy of this page if paying by deposit account)     </li> </ol>		
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9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.			
67. WILLIAM S. FROMMER	December 15, 1998		
Name of Person Signing	Signature Date		
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## ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

APPARATUS AND METHOD FOR MEASURING CHARACTERISTICS OF OPTICAL PICKUP AND/OR OPTICAL DISC

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address:

AND WHEREAS, Sony Precision Engineering Center (S) Pte. Ltd., a Singapore corporation, with offices at 52 Tuas Avenue 9, Singapore 639193, Disk Ware Co. Ltd., a Japanese corporation, with offices at Nakoji Kiba Bldg. 2F, 1-4-12 Kiba, Koto-ku, Tokyo 135-0042, Japan and Sony Corporation, a Japanese corporation, with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-ku, Tokyo 141, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries:

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or join: inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said interest in the said application, including any divisions and continuations thereof and in and to apply and all letters Patent of the United States and continuations for any sole and all letters Patent of the United States and continuations for any sole and all letters patent of the United States. and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convent on rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto:

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto:

And I hereby covenant that no assignment, sale, agreement or encumbrance has beer or will be made or entered into which would conflict with this assignment and sale.

number and filing date of this application in the spaces that follow: Serial Number: \_\_\_\_\_, Fil ng Date: \_\_\_\_\_

And I hereby authorize and request my attorney(s) of record in this application to insert the serial This assignment executed on the dates indicated below. Akihito NAKAYAMA Name of first or sole inventor Execution date of U.S. Patent Application 205 River Valley Road #10-54, UE Square, Singapore 238274 Residence of first or sole inventor NUV 1998 Signature of first or sole in Kenji SHINTANI Name of second inventor Execution date of U.S. Patent Application 8 Chancery Lane #03-03, Singapore 309494 Residence of second inventor Din Shitz-Znd NOV 1998 Signature of second inventor Shunsuke KOHAMA Name of third inventor Execution date of U.S. Patent Application 468-519 Sonnou Inage-ku, Chiba City, Chiba, Japan Residence of third inventor Signature of third inventor

J. SONY 4655:APPRECC MSP. (WSF:lm)

PATENT Page 1 of 2

REEL: 9650 FRAME: 0257

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Residence of fifth inventor  Lides Fully	L 17. Th. Nov. 1978	
Signature of fifth inventor	Date of this assignment	

**RECORDED: 12/18/1998** 

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